



# MULTILAYER CERAMIC CAPACITORS

High Q / Low ESR Series (HH) 0201 to 0805 Sizes NP0 Dielectric Halogen Free & RoHS Compliance

\*Contents in this sheet are subject to change without prior notice.

### **1. INTRODUCTION**

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

WTC HH series MLCC is used at high frequencies generally have a small temperature coefficient of capacitance, typical within the  $\pm 30$  ppm/°C required for NP0 (C0G) classification and have excellent conductivity internal electrode. Thus, WTC HH series MLCC will be with the feature of low ESR and high Q characteristics.

### 2. FEATURES

- a. High Q and low ESR performance at high frequency.
- b. Quality improvement of telephone calls for low power loss and better performance.

### **3. APPLICATIONS**

- a. Mobile telecommunication: Mobile phone, WLAN.
- b. RF module: Power amplifier, VCO.
- c. Tuners.

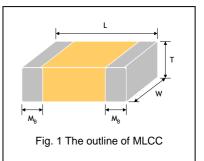
## 4. HOW TO ORDER

<u>HH</u>	<u>15</u>	N	<u>100</u>	G	<u>500</u>	<u>C</u>	Ī
<u>Series</u>	<u>Size</u>	<b>Dielectric</b>	Capacitance	Tolerance	Rated voltage	Termination	Packaging
<u>Series</u> HH=High Q/ Low ESR	<u>SIZE</u> 03=0201 (0603) 15=0402 (1005) 18=0603 (1608) 21=0805 (2012)	Dielectric N=NP0 (COG)	Capacitance Two significant digits followed by no. of zeros. And R is in place of decimal point. PASSIVE SY eg.: R47=0.47pF 0R5=0.5pF 1R0=1.0pF 100=10x10 <sup>0</sup> =10pF	Interface   A=±0.05pF   B=±0.1pF   C=±0.25pF   D=±0.5pF   F=±1%   G=±2%   J=±5%	Two significant digits followed by no. of zeros. And R is in place of decimal point.	C=Cu/Ni/Sn	Packaging T=7" reeled G=13" reeled
					631=630 VDC		

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# **5. EXTERNAL DIMENSIONS**

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbol		Remark	M <sub>B</sub> (mm)	
0201 (0603)	0.6±0.03	0.3±0.03	0.3±0.03	L	#	0.15±0.05	
0402 (1005)	1.00±0.05	0.50±0.05	0.50±0.05	N	#	0.25 +0.05/-0.10	
	1.60±0.10	0.80±0.10	0.80±0.07 S				
0603 (1608)	1.60 +0.15/-0.10	0.80 +0.15/-0.10	0.80 +0.15/-0.10	x		0.40±0.15	
			0.60±0.10	A			
0805 (2012)	2.00±0.15	1.25±0.10	0.80±0.10	В		0.50±0.20	
"D."			1.25±0.10	D	#		



# Reflow soldering only is recommended.

# 6. GENERAL ELECTRICAL DATA

Dielectric	NPO				
Size	0201, 0402, 0603, 0805				
Capacitance*	0.1pF to 3300pF				
	Cap≤5pF <sup>#</sup> : A (±0.05pF), B (±0.1pF), C (±0.25pF)				
Capacitance tolerance	5pF <cap<10pf: (±0.25pf),="" (±0.5pf)<="" c="" d="" td=""></cap<10pf:>				
	Cap≥10pF: F (±1%), G (±2%), J (±5%) ANCE				
Rated voltage (WVDC)	10V, 16V, 25V, 50V, 100V, 200V, 250V, 500V, 630V				
<b>0</b> *	Cap<30pF: Q≥400+20C				
Q*	Cap≥30pF: Q≥1000				
Insulation resistance at Ur	≥10GΩ or RxC≥100Ω-F whichever is smaller.				
Operating temperature	-55 to +125℃				
Capacitance change	±30ppm				
Termination	Ni/Sn (lead-free termination)				

信章

#1: NP0, 0.1pF product only provide B tolerance

\* Measured at the conditions of 25°C ambient temper ature and 30~70% related humidity.

Apply 1.0±0.2Vrms, 1.0MHz±10% for Cap≤1000pF and 1.0±0.2Vrms, 1.0kHz±10% for Cap>1000pF.

## 7. PACKAGING DIMENSION AND QUANTITY

Size	Thickness (mm)/Sym	Pape	r tape	Plastic tape		
5120	mickness (min)/Sym	7" reel	13" reel	7" reel	13" reel	
0201	0.30±0.03	L	15,000	70,000	-	-
0402	0.50±0.05	N	10,000	50,000	-	-
0000	0.80±0.07	S	4 000	45.000		
0603	0.80 +0.15/-0.10	Х	4,000	15,000	-	-
	0.60±0.10	A	4 000	45.000		
0805	0.80±0.10	В	4,000	15,000	-	-
	1.25±0.10	D	-	-	3,000	10,000
			•		•	Linit: nic

Unit: pieces

Approval Sheet

Page 3 of 11

ASC\_HQ\_Low ESR\_(HH)\_006V\_AS



# **8. CAPACITANCE RANGE**

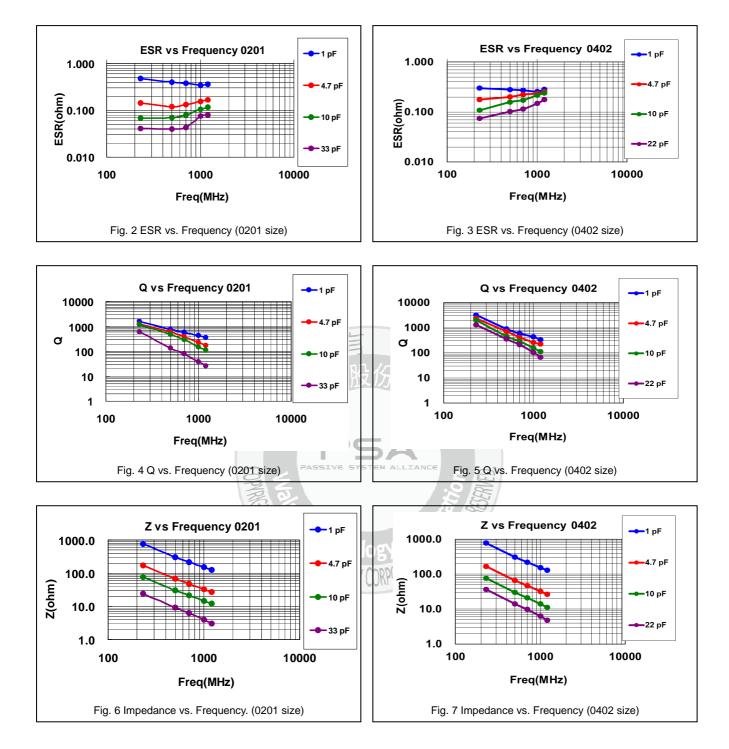
	DIELECTRIC										NP0									
	SIZE		02	01			04	02				0603						05		
	Rated Voltage	10	16	25	50	16	25	50	100	16	25	50	100	200	50	100	200	250	500	630
	0.1pF (0R1)					Ν	N	N	N											
	0.2pF (0R2)					Ν	N	N	N											
	0.3pF (0R3)	L	L	L	L	Ν	N	N	N											
	0.4pF (0R4)	L	L	L	L	Ν	N	N	N											
	0.5pF (0R5)	L	L	L	L	Ν	N	N	N	S	S	S	S	S	В	В				L
	0.6pF (0R6)	L	L	L	L	N	N	N	N	S	S	S	S	S	В	В				
	0.7pF (0R7)		L	L	L	N	N	N	N	S	S	S	S	S	В	B				
	0.8pF (0R8)	L	L	L	L	N	N	N	N	S	S	S	S	S	B	B				
	0.9pF (0R9)	L	L	L	L	N	N	N	N	S	S	S	S	S	B	B	_			<b>D</b>
-	1.0pF (1R0)		L	L		N	N	N	N N	S S	S	S S	S	S S	B	B	B	B	B	B
	1.2pF (1R2)		L	L	L	N	N	N N	N	S	S	S	S S	S	B	B	B	B	B	B
	1.5pF (1R5)		L	L	L	N N	N N	N	N	S	S S	S	S	S	B	B	B	B B	B	B
	1.8pF (1R8)		L		L					S		S	S	S	В		В		B	
	2.2pF (2R2)	 	L	L	L	N N	N N	N N	N N	S S	S S	S	S	S	B	B B	B	B	B	B
	2.7pF (2R7) 3.3pF (3R3)	 	L	L	L	N N	N	N	N	S	S	S	S	S	B	B	B	B	B	B
	3.9pF (3R9)	L	L	L	L	N	N	N	N	S	S	S	S	S	B	B	B	B	B	B
	4.7pF (4R7)	L	L	L	L	N	N	N/	N	S	S	S	S	S	B	B	B	B	B	B
	5.6pF (5R6)	L	L	L	L	N .	N	N	N	S	S	S	S	S	B	B	B	B	B	B
	6.8pF (6R8)	 	L	L	L	N	N	N	ΠN/	S	S	S	S	S	B	B	B	B	B	B
	8.2pF (8R2)		L	L	Ē	ŃN	N	N	$\sum_{N}$	7 s\$	S	s	S	S	В	В	В	В	B	В
	10pF (100)		L	L	14N	N	N	N	N	S	ŚŚ	S	S	S	В	В	В	В	B	B
-	12pF (120)	L	L	L	1721	7 N	N	N	N	S	S	S	S		В	В	В	В	В	В
	15pF (150)	L	L	L	L	N	N	N	N	S	S	s	S		В	В	В	В	В	В
e	18pF (180)	L	L	L	L	Ň	N	N	N	S	S	S	S		В	В	В	В	В	В
tan	22pF (220)	L	L	L	L	Ν	N	N	N	S	S	S	S		В	В	В	В	В	В
aci	27pF (270)	L	L	L	B	Ν	PASS: N	IVE S	N	S	S	S	Ś		В	В	В	В	В	В
Capacitance	33pF (330)	L	L	L	F	N	N	N	N	S	S	S ;	S		В	В	В	В	В	В
	39pF (390)				0	N	N	N	N	S	S	SS	S		В	В	В	В	В	В
	47pF (470)					<u>о</u> N	) N	Ν	N	S	S	S	S		В	В	В	В	В	В
	56pF (560)				6	N	N.	N	N	S.	S	S	S		В	В	В	В	В	В
	68pF (680)					N	∕ N	N (	) N 2	S	S	S	S		В	В	В	В	В	В
	82pF (820)					N	/N/	N	Ν	S	S	S	S		В	В	В	В	В	В
	100pF (101)					Ν	N.	N	YNK	P S M	S	S	S		В	В	В	В	В	В
	120pF (121)					Ν	N	Ν	Ν	S	S	S	S		D	D	D	D	D	D
	150pF (151)					Ν	N	N	N	S	S	S	S		D	D	D	D	D	D
	180pF (181)					N	N	N	N	S	S	S	S				D	D	D	D
	220pF (221)					N	N	N	N	S	S	S	S				D	D	D	D
	270pF (271)					N	N	N		S	S	S	S				D	D	D	D
	330pF (331)					N	N	N		S	S	S	S				D	D	D	D
	390pF (391)					N	N	N		S S	S S	S S	S S				D	D	D	D
	470pF (471)					Ν	Ν	N		S	S	S	S							
	560pF (561) 680pF (681)									S	S	S	S							
	820pF (881)									S	S	S	S							
	1,000pF (102)									S	S	S	S							
	1,200pF (102)									X	X	X								
	1,500pF (122)									X	X	X								
	1,800pF (182)									X	X	X								
	2,200pF (222)									X	X	X								
	2,700pF (272)									X	X	X								
	3,300pF (332)									X	X	X								
4 Th	le letter in cell is ex					roduc	t thick			. · ·			1	1	I			1		

1. The letter in cell is expressed the symbol of product thickness.

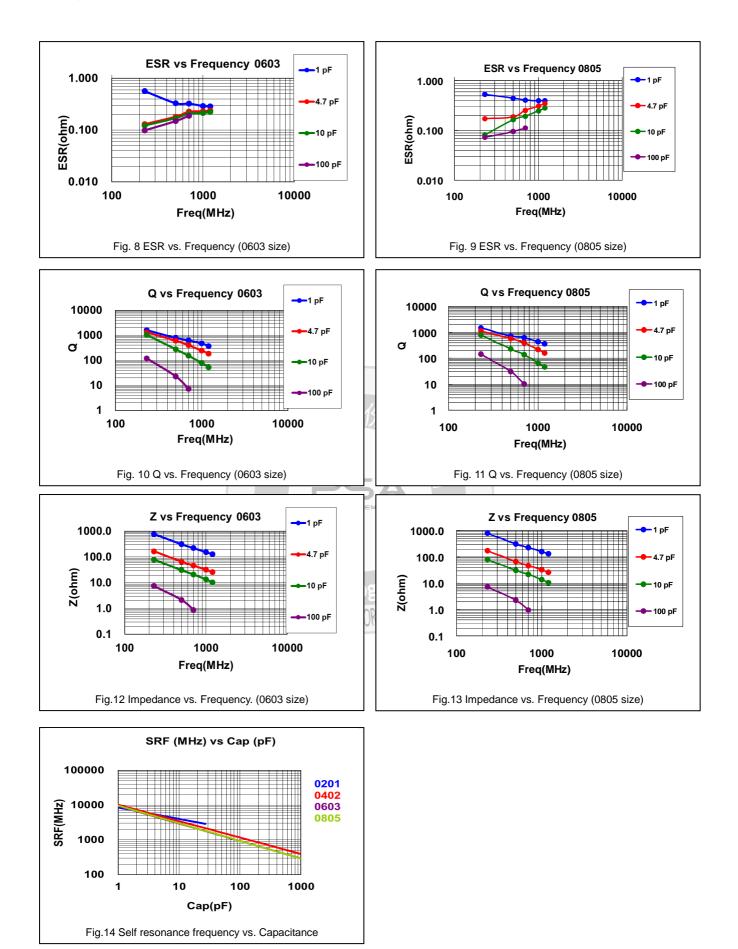
2. For more information about products with special capacitance or other data, please contact WTC local representative.



# 9. ELECTRICAL CHARACTERISTICS



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ASC\_HQ\_Low ESR\_(HH)\_006V\_AS

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# **10. RELIABILITY TEST CONDITIONS AND REQUIREMENTS**

No.	ltem	Test Conditions	Requirements
1.	Visual and		* No remarkable defect.
	Mechanical		* Dimensions to conform to individual specification sheet.
2.	Capacitance	Cap≤1000pF, 1.0±0.2Vrms, 1MHz±10%	* Shall not exceed the limits given in the detailed spec.
3.	Q/ D.F.	Cap>1000pF, 1.0±0.2Vrms, 1KHz±10%	* NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C
	(Dissipation	At 25℃ ambient temperature.	
	Factor)		
4.	Dielectric	* To apply voltage: ( ≤100V ) 250% of rated voltage.	* No evidence of damage or flash over during test.
	Strength	* Duration: 1 to 5 sec.	
		* Charge and discharge current less than 50mA.	
		* To apply voltage:	
		200V~300V ≥2 times VDC	
		500V~999V ≥1.5 times VDC	
		* Cut-off, set at 10mA	
		* TEST= 15 sec.	
		* RAMP=0	
5.	Insulation	Rated voltage:<200V	≥10GΩ
	Resistance	To apply rated voltage for max. 120 sec.	
		Rated voltage:200~630V	≥10GΩ or RxC≥100Ω-F whichever is smaller
		To apply rated voltage (500V max.) for 60 sec.	×
6.	Temperature	With no electrical load.	* Capacitance change: within ±30ppm/℃
	Coefficient	Operating temperature: -55~125℃ at 25℃	
7.	Adhesive	* Pressurizing force :	* No remarkable damage or removal of the terminations.
	Strength of	2N (0201) and 5N (≤0603) and 10N (>0603)	
	Termination	* Test time: 10±1 sec.	
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.
	Resistance	* Total amplitude: 1.5mm	* Cap change and Q/D.F.: To meet initial spec.
		* Test time: 6 hrs. (Two hrs each in three mutually	
		perpendicular directions.)	
		* Cap./DF(Q) Measurement to be made after de-aging at	
		150°C for 1hr then set for $24\pm 2$ hrs at room temp.	AQ ASS
9.	Solderability	* Solder temperature: 235±5℃	95% min. coverage of all metalized area.
		* Dipping time: 2±0.5 sec.	
10.	Bending Test	* The middle part of substrate shall be pressurized by means	* No remarkable damage.
	_	of the pressurizing rod at a rate of about 1 mm per second until	* Cap change: within ±5.0% or ±0.5pF whichever is larger.
		the deflection becomes 1 mm and then the pressure shall be	(This capacitance change means the change of capacitance under
		maintained for 5±1 sec.	specified flexure of substrate from the capacitance measured before
		* Measurement to be made after keeping at room temp. for	the test.)
		24±2 hrs.	
11.	Resistance to	* Solder temperature: 260±5℃	* No remarkable damage.
	Soldering Heat		* Cap change: within ±2.5% or ±0.25pF whichever is larger.
	J J	* Preheating: 120 to 150°C for 1 minute before immerse the	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.
		capacitor in a eutectic solder.	* 25% max. leaching on each edge.
		* Cap. / DF(Q) / I.R. Measurement to be made after de-aging	
		at 150°C for 1hr then set for 24±2 hrs at room temp.	

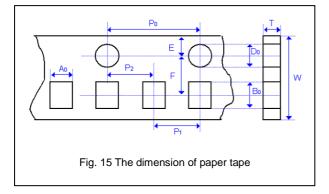


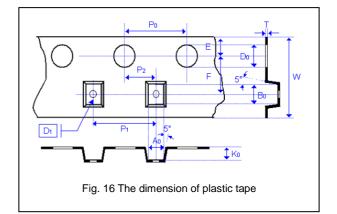
ltem	Test Condition	n	Requirements				
timo	nduct the five cycles according to th	ne temperatures and	No remarkable damage.				
ycie	tep Temp. (°C)	Time (min.)	* Cap change : within ±2.5% or ±0.25pF whichever is larger.				
	1 Min. operating temp. +0/-3	30±3	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.				
	2 Room temp.	2~3					
	3 Max. operating temp. +3/-0	30±3					
	4 Room temp.	2~3					
* Cap	p. / DF(Q) / I.R. Measurement to be	made after de-aging					
	50℃ for 1hr then set for 24±2 hrs at	room temp.					
lumidity * Test	t temp.: 40±2℃		* No remarkable damage.				
Damp Heat) * Hun	midity: 90~95% RH		* Cap change: within $\pm 5.0\%$ or $\pm 0.5$ pF whichever is larger.				
teady State * Test	t time: 500+24/-0hrs.		* Q/D.F. value:				
* Cap	p. / DF(Q) / I.R. Measurement to be	made after de-aging	NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C				
at 150	50℃ for 1hr then set for 24±2 hrs at	room temp.	Cap<10pF; Q≥200+10C				
			* I.R.: $\geq 1G\Omega$ or RxC $\geq 50\Omega$ -F whichever is smaller.				
lumidity * Test	t temp.: 40±2℃		* No remarkable damage.				
Damp Heat) * Hun	midity: 90~95%RH		* Cap change: within ±7.5% or ±0.75pF whichever is larger.				
.oad * Test	t time: 500+24/-0 hrs.		* Q/D.F. value:				
* To a	apply voltage : rated voltage (Max.	500V)	NP0: Cap≥30pF, Q≥200; Cap<30pF, Q≥100+10/3C				
* Cap	p. / DF(Q) / I.R. Measurement to be	made after de-aging	* I.R.: ≥500MΩ or RxC≥25Ω-F whichever is smaller.				
at 15	50℃ for 1hr then set for 24±2 hrs at	t room temp.	THE STREET				
ligh * Test	t temp.:	11 /0	* No remarkable damage.				
emperature NP0	0: 125±3℃	、	* Cap change: within ±3.0% or ±0.3pF whichever is larger.				
.oad * To a	apply voltage:	XV	* Q/D.F. value:				
Endurance) (1) <5	500V: 200% of rated voltage.		NP0: Cap≥30pF, Q≥350				
(2) 50	00V: 150% of rated voltage.		10pF≤Cap<30pF, Q≥275+2.5C				
(3) ≥€	630V: 120% of rated voltage.		Cap<10pF, Q≥200+10C				
* Tesf	t time: 1000+24/-0 hrs.		* I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.				
* Cap	p. / DF(Q) / I.R. Measurement to be	made after de-aging					
at 15	50℃ for 1hr then set for 24±2 hrs at	room temp.	.9 2				
* Cap	p. / DF(Q) / I.R. Measurement to be i0°C for 1hr then set for 24±2 hrs at						

### **APPENDIXES**



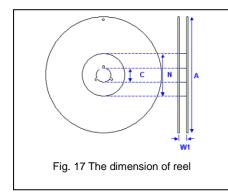
### Tape & reel dimensions





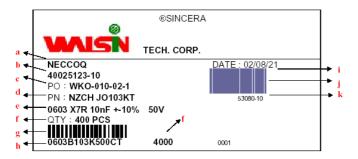
Size	0201	0402	0603		0805	
Thickness	L	N	S, X	A	В	C, D, I
Ao	0.40 +/-0.10	0.70 +/-0.20	1.05	1.50 +/-0.20	1.50 +/-0.20	< 1.80
Bo	0.70 +/-0.10	1.20 +/-0.20	1.80 +/-0.30	2.30 +/-0.20	2.30 +/-0.20	< 2.70
т	≦0.55	≦0.80	5 ≦1.20	≦1.15	≦1.20	0.23 +/-0.1
Ko	-	the second		Fi	-	< 2.50
w	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30	8.00	8.00 +/-0.30	8.00 +/-0.30
Po	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10
10xP₀	40.00 +/-0.10	40.00 +/-0.10	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20
P <sub>1</sub>	2.00 +/-0.05	2.00 PASSIV	E SYSTE4.00 LLIANC +/-0.10	4.00	4.00 +/-0.10	4.00 +/-0.10
P <sub>2</sub>	2.00 +/-0.05	2.00	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05
Do	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0
D <sub>1</sub>	-	Chi	01		-	1.00 +/-0.10
E	1.75 +/-0.10	1.75 +/-0.10	1.75 (+/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10
F	3.50 +/-0.05	3.50 +/-0.05	3.50	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05

TOTOPI CORPONENT



Size	0201, 0402, 0603, 0805							
Reel size	7"	10"	13"					
С	13.0+0.5/-0.2	13.0+0.5/-0.2	13.0+0.5/-0.2					
<b>W</b> <sub>1</sub>	8.4+1.5/-0	8.4+1.5/-0	8.4+1.5/-0					
Α	178.0±1.0	250.0±1.0	330.0±1.0					
N	60.0+1.0/-0	100.0±1.0	100±1.0					

### Example of customer label



\*Customized label is available upon request

- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer

Approval Sheet

- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

### Constructions

No.	Na	ime	NP0	$\neg$	
1	Ceramic	material	CaZrO <sub>3</sub> based		
2	Inner e	lectrode	HE HIN AL		
3		Inner layer	Cu El	7.3	
4	Termination	Middle layer	Ni	र्ट्रत	0
5		Outer layer			Fig. 18 The construction of MLCC
			PASSTVE SYSTEM ALL TANCE		

### Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

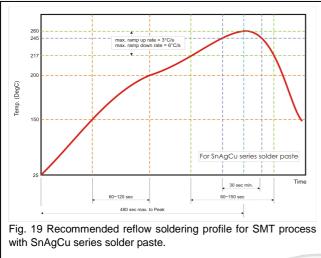
#### Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.



### Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of  $N_2$  within oven are recommended.



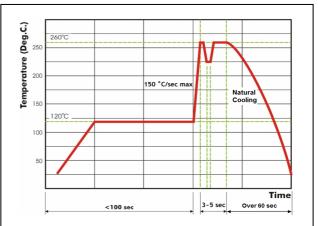


Fig. 20 Recommended wave soldering profile for SMT process with SnAgCu series solder.

